

恒拓电子
HENG TUO ELECTRONICS

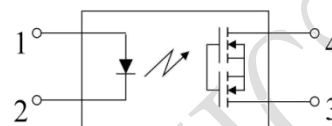
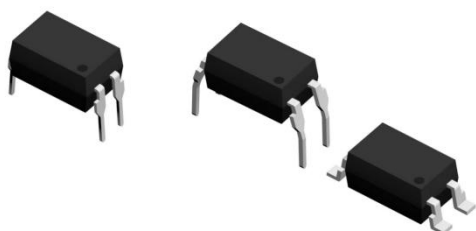


HT series

**Photo Coupler
Product Specification**

HTV-21X

■ Package



Pin Configuration

1. AN
2. CA
3. D1
4. D2

■ Description

The HTV-21X is solid state relays containing an AlGaAs infrared LEDs on the light emitting side (input side) optically coupled to a high voltage output detector circuit. The detector consists of a photovoltaic diode array and MOSFETs on the output side. The single channel configuration is equivalent to 1 form A EMR. The devices in a 4-pin small outline SMD package.

■ Features

- Normally open signal pole signal throw relay
- Low operating current
- 60 to 600V output withstand voltage
- Wide operating temperature range of -40°C to 85°C
- High input-output isolation voltage(Viso = 5,000Vrms)
- Safety approval
(UL 1577, VDE DIN EN60747-5-5 (VDE 0884-5) , CQC11-471543-2022)
- RoHS
- MSL1

■ Applications

- Measurement equipment
- Exchange equipment
- FA/OA equipment
- Security
- Industrial controls

■ Product Nomenclature

The product name is designated as below:

HTV -21X -X X- X X- XX

① ② ③ ④ ⑤

Designation:

HT =Hengtuo Technology Co.,LTD.

V =Dip4 Package type

21X= Product Series(212,213,214,216)

① = Lead form option(S1,M,NONE)₍₁₎

② = Tape and Reel option(TP,TP1,NONE)₍₂₎

③ = VDE order option(fixed code "V")

④ = Halogen free option(fixed code"G")

⑤ = Customer code

Notes

1. Lead form option:

Symbol	Description
S1	DIP4-S1
M	DIP4-M
NONE	DIP4 Normal

2. Tape and Reel option:

Symbol	Description
TP&TP1	Tape and Reel Type
NONE	DIP Type

■ Marking Information



Designation:

HT denotes Hengtu
V denotes Dip 4 Package type
21X denotes Device
YY denotes year code
WW denotes week code
V denotes VDE

■ Maximum Ratings

Parameter		Symbol	Values	Unit
Input	Forward Current	I_F	50	mA
	Reverse Voltage	V_R	6	V
	Power Dissipation	P	75	mW
	Peak Forward Current (100μs pulse, 100Hz)	I_{FP}	1	A
	Thermal Resistance Junction-Ambient	R_{thJ-A}	325	°C/W
	Thermal Resistance Junction-Case	R_{thJ-C}	200	°C/W
Output	Break Down Voltage	V_L	HTV-212 60	V
			HTV-213 100	
			HTV-214 400	
			HTV-216 600	
	Continuous Load Current	I_L	HTV-212 550	mA
			HTV-213 180	
			HTV-214 120	
			HTV-216 50	
	Pulse Load Current ^{*(1)}	I_{LPeak}	HTV-212 1.2	A
			HTV-213 0.5	
			HTV-214 0.3	

HTV-216 0.15			
Power Dissipation	P_{out}	500	mW
Operating temperature range	T_{op}	-40 ~ 85	°C
Storage temperature range	T_{stg}	-40 ~ 125	°C
Total Power consumption	$P(W)$	550	mW
Isolation Voltage ⁽²⁾	V_{ISO}	5000	Vrms
Soldering Temperature ⁽³⁾	T_{SOL}	260	°C

Notes:

(1). A connection: 100ms (1 shot), $V_L = DC$

(2)AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

(2).For 10 seconds

■ Electronic Optical Characteristics

($T_A = 25^\circ C$)

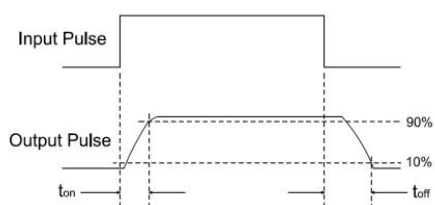
Parameter		Symb ol	Min.	Typ.	Max.	Unit	Conditon
Input	Forward Voltage	V_F	-	1.2	1.5	V	$I_F = 10mA$
	Reverse Current	I_R	-	-	1	μA	$V_R = 5V$
Output	Off State leakage Current	I_{leak}	-	-	1	μA	$I_F = 0mA$, $V_L = Max$
	On Resistance	$R_{d(ON)}$	-	0.7	2.5	Ω	$I_F = 10mA$, $I_L = Max$. $t = 1s$
			-	6.5	15		
			-	20	30		
			-	40	70		
	Output Capacitance	C_{out}	-	80	-	pF	$V_L = 0V$, $f = 1MHz$
			-	60	-		
			-	45	-		
			-	30	-		
Transfer Characteristics	LED turn on Current	$I_{F(on)}$		2.5	5	mA	$I_L = Max.$
	LED turn off	$I_{F(off)}$	0.4	2.5	-	mA	$I_L = Max.$

current					
Turn On Time	HTV-212	T_{ON}	-	1.4	3
	HTV-213		-	1.2	3
	HTV-214		-	0.4	3
	HTV-216		-	1.4	3
Turn Off Time	HTV-212	T_{OFF}	-	0.05	0.5
	HTV-213		-	0.05	0.5
	HTV-214		-	0.05	0.5
	HTV-216		-	0.05	0.5

ms

$I_F = 10 \text{ mA}$,
 $I_L = \text{Max.}$ $R_L = 200 \Omega$,

Turn on/Turn off Time



■ Characteristics Curves

Fig.1 LED Dropout Voltage vs. Ambient Temperature

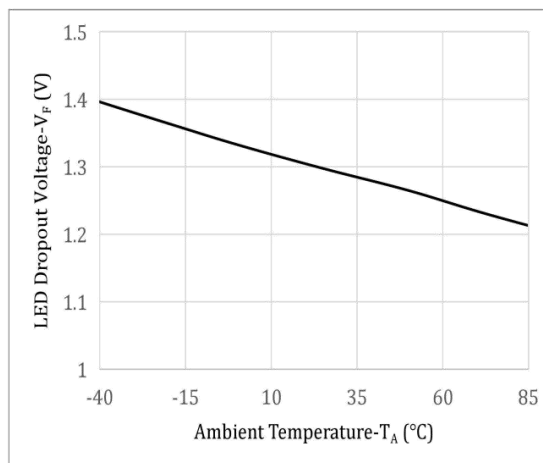


Fig.2 Output Current vs. Output Voltage

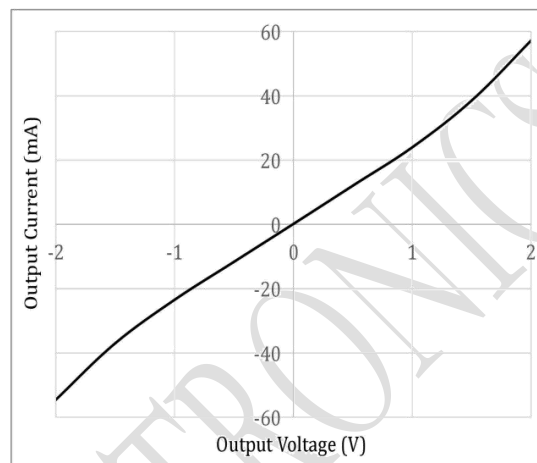


Fig.3 On Resistance vs. Ambient

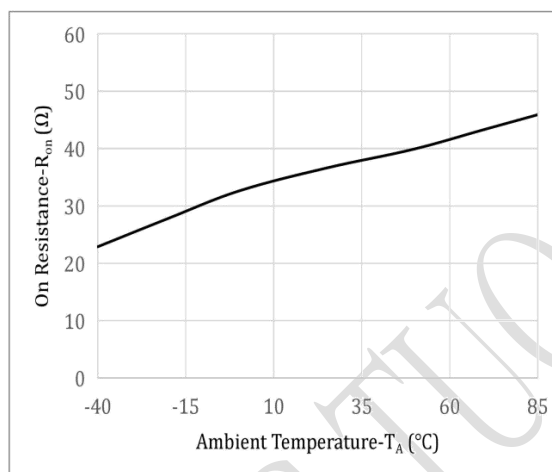


Fig.4 Load Current vs. Ambient Temperature

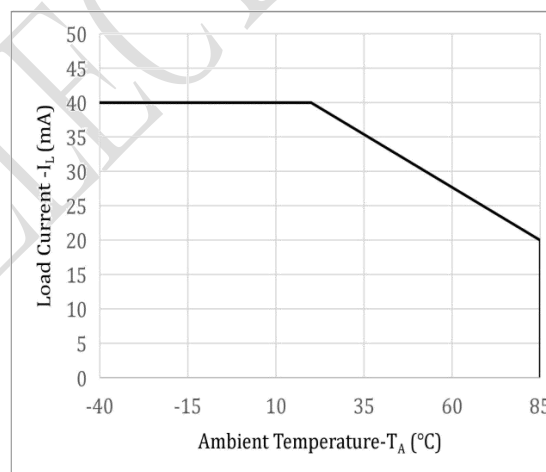


Fig.5 LED Operate Current vs. Ambient Temperature

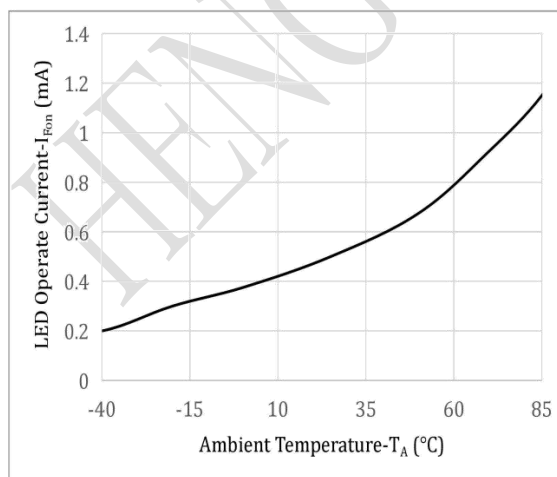


Fig.6 LED Turn Off Current vs. Ambient

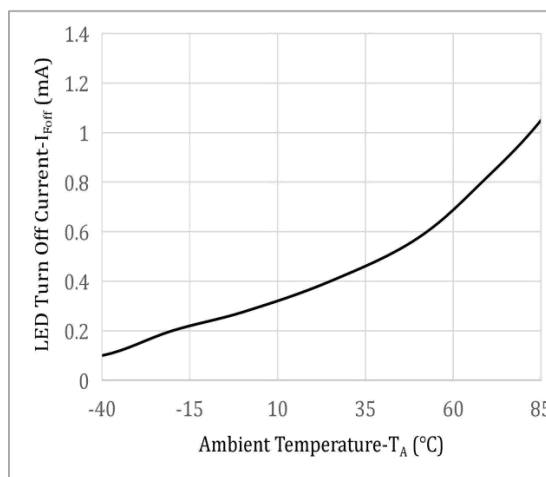


Fig.7 Turn On Time vs. Ambient Temperature

Fig.8 Turn Off Time vs. Ambient Temperature

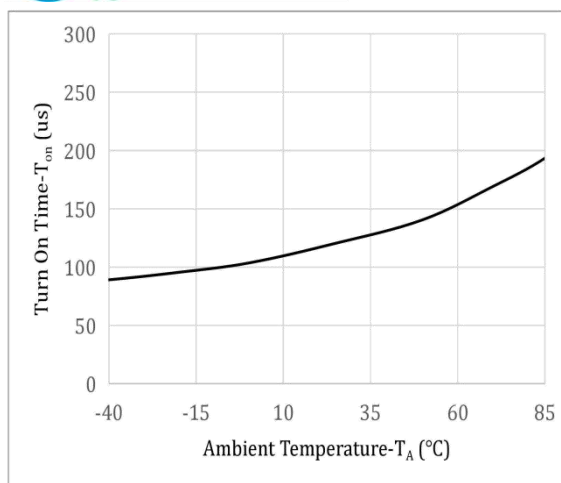


Fig.9 Turn On Time vs. LED Forward Current

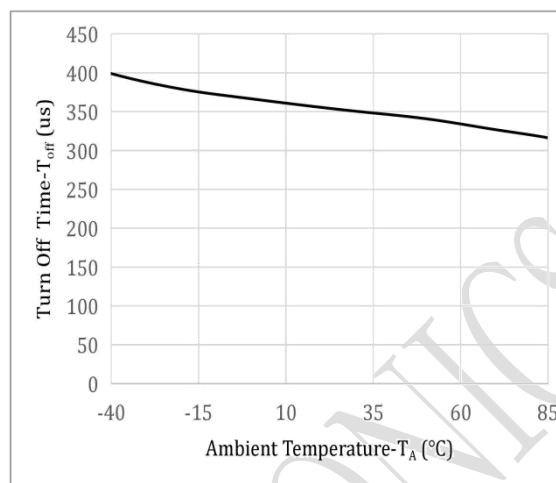


Fig.10 Turn Off Time vs. LED Forward

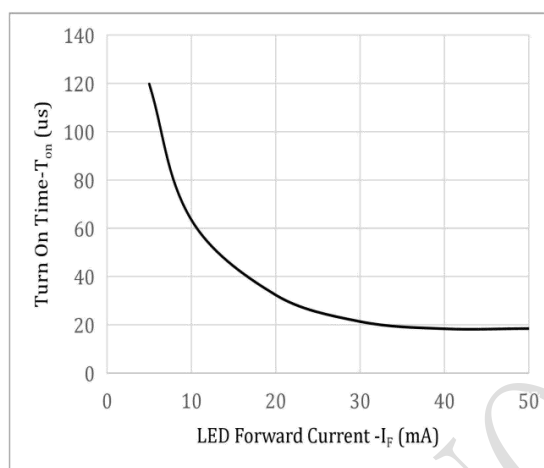
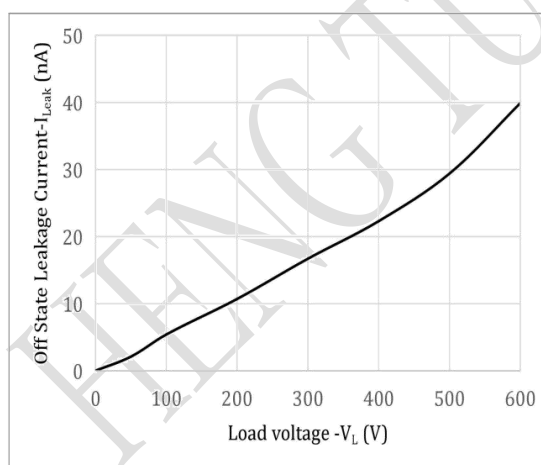
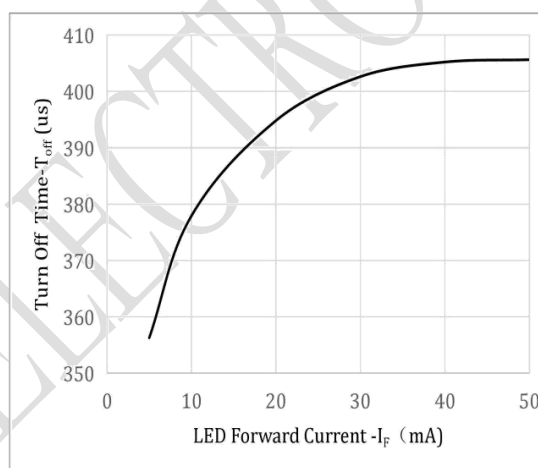
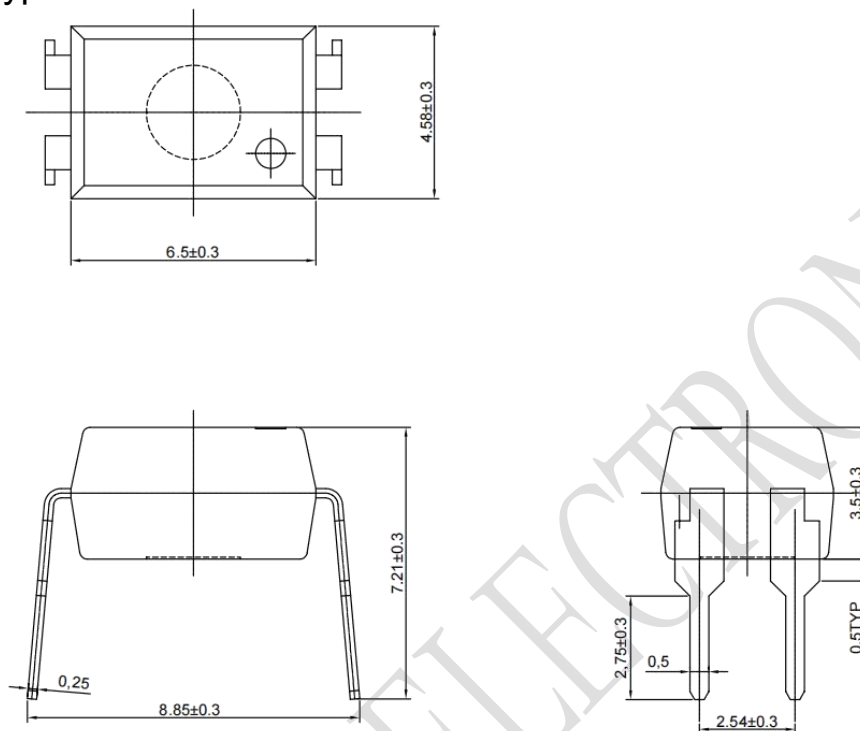


Fig.11 Off State Leakage Current vs Load Voltage

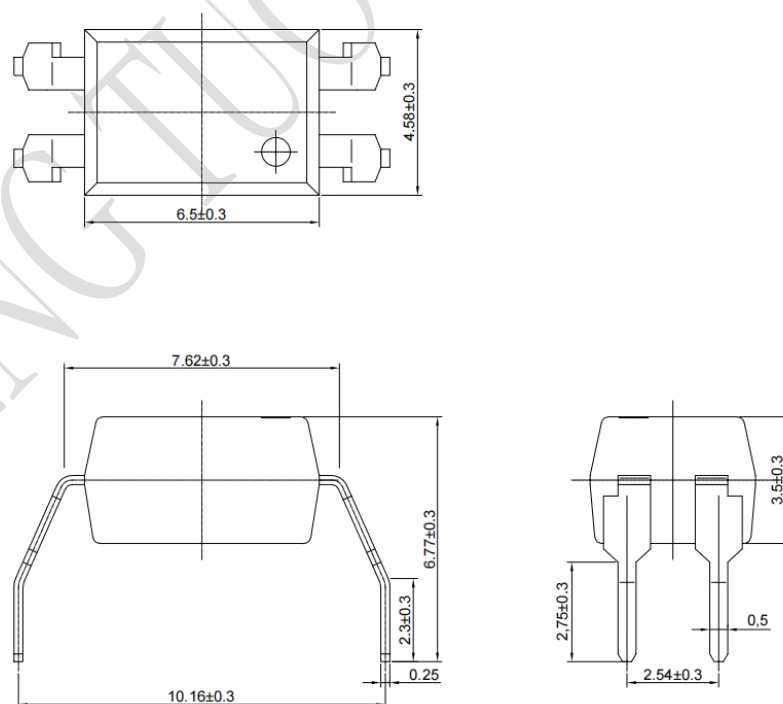


■ Outline Dimension

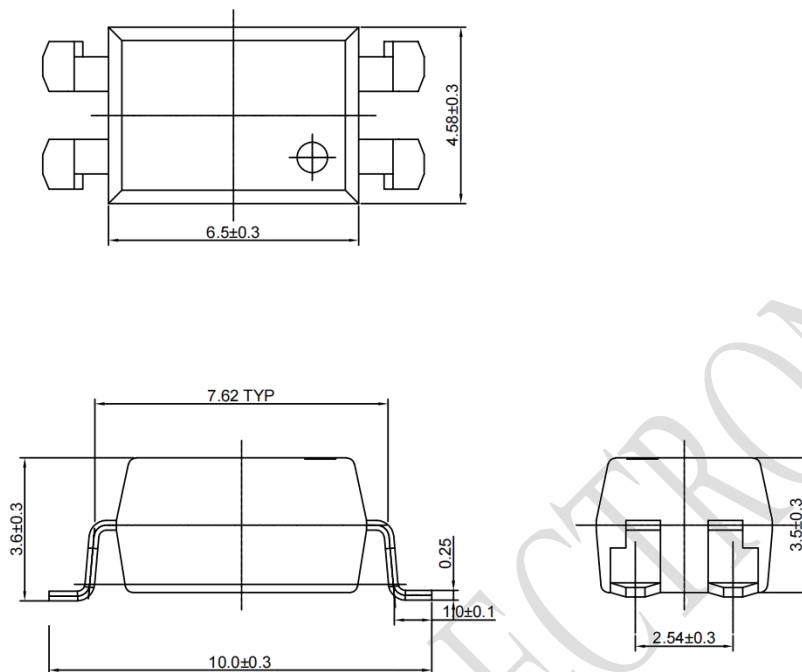
DIP Normal Type:



DIP M Type:



SMD S1 Type:

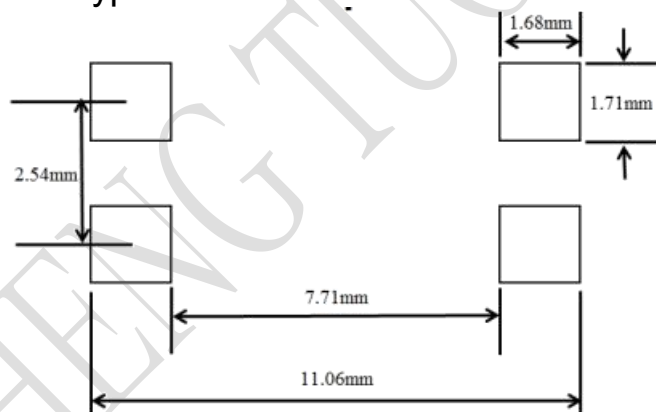


Unit: mm

Tolerance: ± 0.1 mm

■ Recommended solder pad Design

For S1 type:



Unit: mm

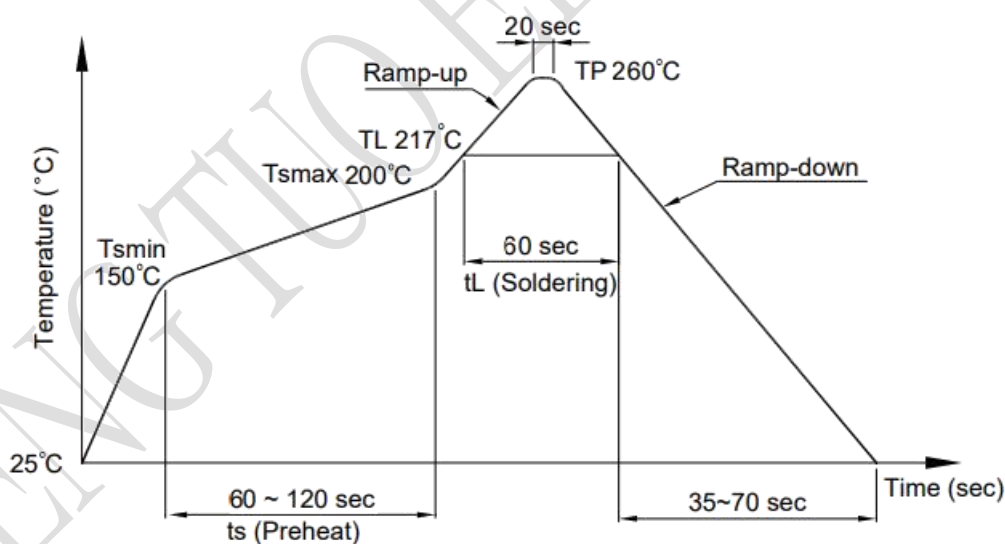
Tolerance: ± 0.1 mm

■ Temperature Profile Of Soldering

1. IR Reflow soldering

(JEDEC-STD-020 compliant)

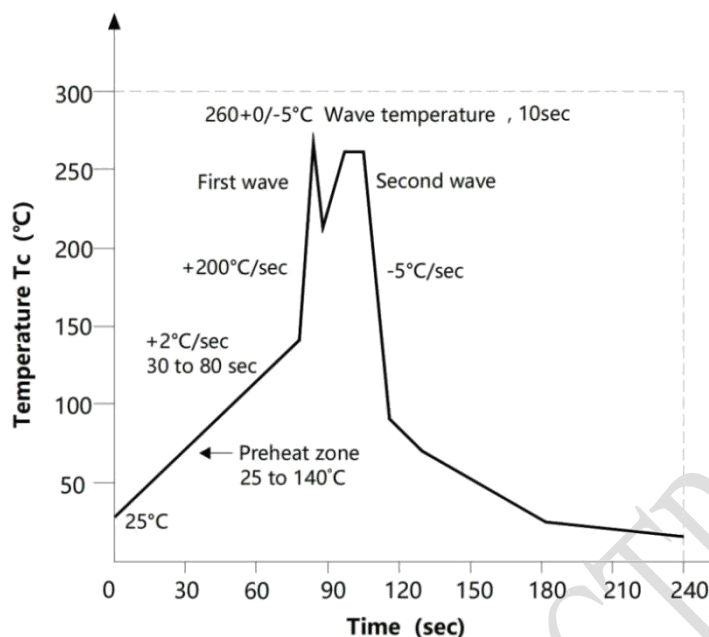
Profile item	Conditon
Preheat	150°C
-Temperature Min (TSmin)	200°C
-Temperature Max (TSmax)	90 ± 30 sec
-Time (min to max) (ts)	
Soldering zone	217°C
-Temperature (TL)	60 sec
-Time (tL)	
Peak Temperature (TP)	260°C
Ramp-up rate	3°C / sec max
Ramp-down rate	3~6°C/ sec



Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

2. Wave soldering (JEDEC22A111 compliant)



3. Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

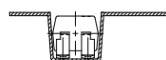
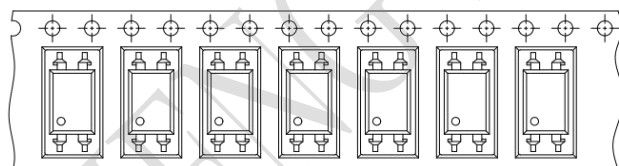
Temperature: $380 \pm 5^\circ\text{C}$

Time: 3 sec max.

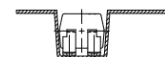
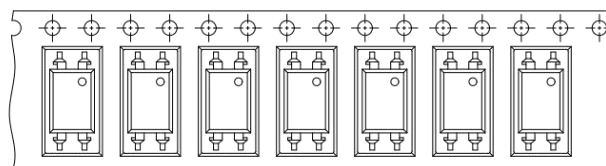
■ Packing

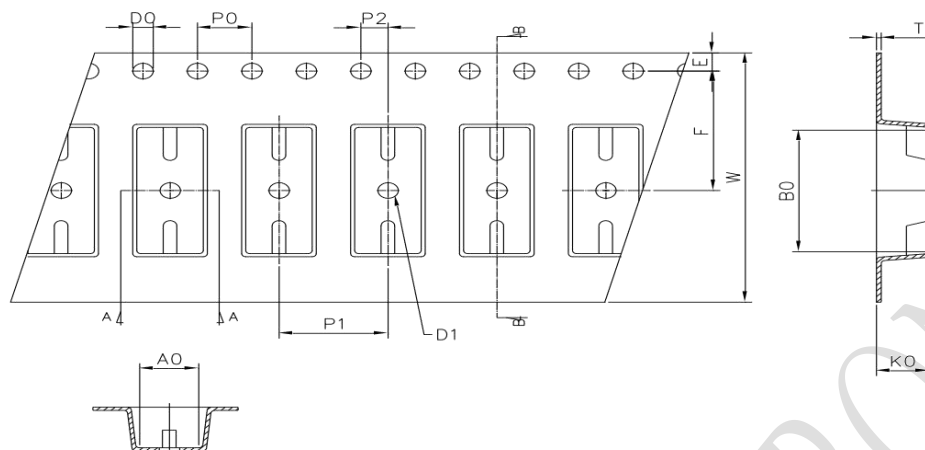
1. Tape and Reel

Option TP:



Option TP1:





Deminsion/mm	W	E	F	P0	P1	P2
Packagetype:S	16 ± 0.2	1.75 ± 0.1	7.5 ± 0.1	4 ± 0.1	8 ± 0.1	2 ± 0.1

Deminsion/mm	A0	B0	D0	D1	K0	T
Packagetype:S	4.6 ± 0.1	10.4 ± 0.1	1.5 ± 0.1	1.5 ± 0.1	4.6 ± 0.1	0.4 ± 0.1

Packagetype:S	Reel	Inner carton	Outer carton
QTY/PCS	1.5K/reel	3K(2 reels)	30K

2. Tape and Tube

Packagetype:Normal&M	Tube	Outer carton
QTY/PCS	100	50K(50 tubes)

■ Attention:

- Hengtuo is continually improving the quality, reliability, function or design and Hengtuo reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
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- When requiring a device for any "specific" application, please contact our sales in advice.
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